

承認書

APPROVAL SHEETS

客戶名稱 : 鴻海精密工業股份有限公司
MESSRS

品名 : DC POWER JACK
DESCRIPTION

料號 : SHD-5014SGLH6-NS-L2-TR
PART NO

客戶料號 :
CUSTOMER
PART NO

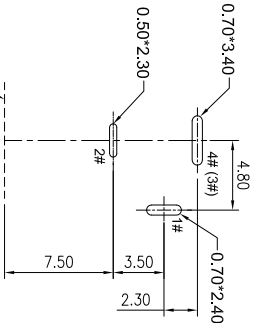
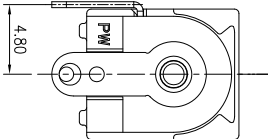
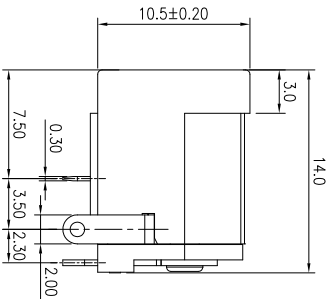
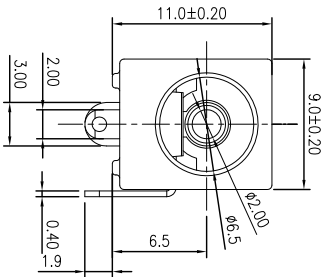
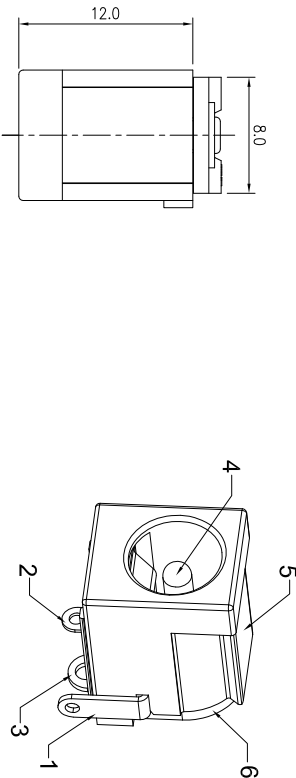
承認印 APPROVED BY



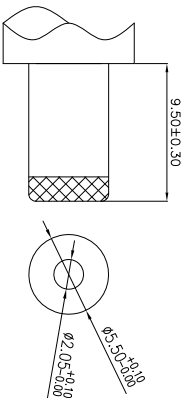
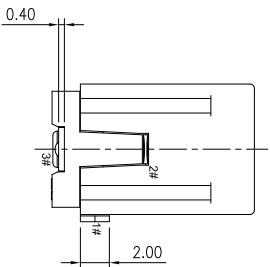
博 歲 電 子 股 份 有 限 公 司
POWERWAY ELECTRONICS CO., LTD.
佳 俊 有 限 公 司
BEST SMART LIMITED
2 4 1 6 1 新北市三重區中華路 18 號 3 樓
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District, New Taipei City 24161, Taiwan
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SHD-5014SGLH6-NS-L2-TR

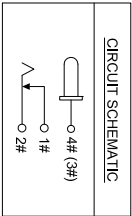
Series
Type
Terminal Plated
N : Nickel-Plated
Housing Material
L2 : LCP
Terminal Material
S : SUS



PCB EDGE
RECOMMENDED PCB LAYOUT
TOP VIEW
TOLERANCE:±0.05mm
PCB THICKNESS: 1.00±0.05mm



PLUG DIAGRAM (TOL:±0.05)



NO.	Name	Material	Finish
6	Housing Cover	Nylon	
5	Housing	LCP	
4	Center Pin	Brass	Nickel-Plated(30u" Min.)
3	Center Pin Terminal	Brass	Nickel-Plated(30u" Min.)
2	Tip Spring	SUS	Nickel-Plated(30u" Min.)
1	Shunt Terminal	Brass	Nickel-Plated(30u" Min.)

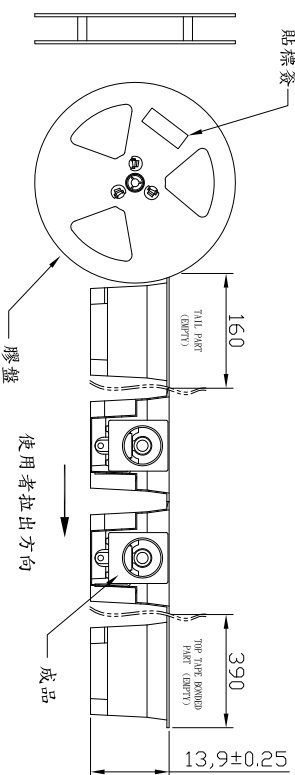
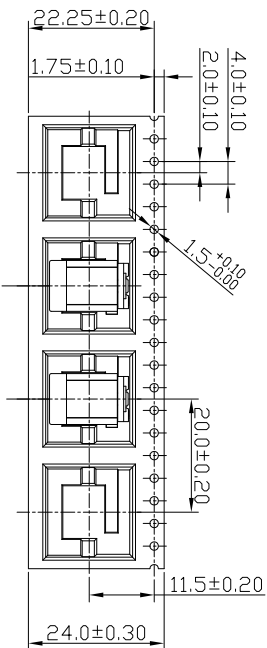
PW 博 威 電 子 有 限 公 司
POWERWAY ELECTRONICS CO.,LTD.

FILE NO.	SHD-5014GL (SERIES)	TITLE	DC, Type A, Receptacle, Horizontal, Single Port, THT
PART NO.	SHD-5014SGLH6-NS-L2-TR	圖 名	

ZONE	REV.	DESCRIPTION	DATE	CHANGE	TOLERANCE(公差): 0.000 mm ± 0.075 mm 0.00 mm ± 0.15 mm 0.0 mm ± 0.25 mm	UNIT 單位	SCALE 比例	REV. 版本	CHECKED BY	DESIGNED BY	APPROVED BY
1	2	3	4	5	6	7	8	9	10	11	12

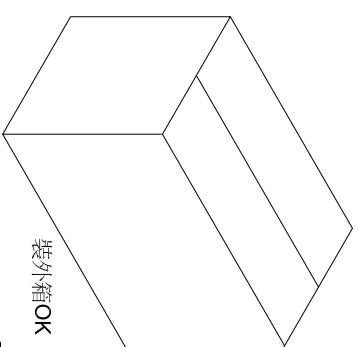
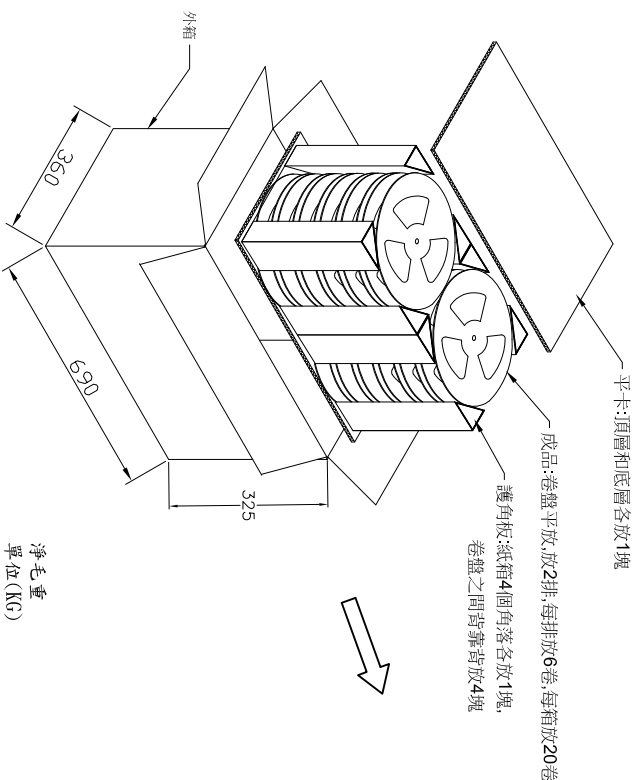
1. 包材:

卷料式包裝帶 1 SET
流程單編號標籤 1 PC
無鉛製程標籤  1 PC
1*210=210 PCS
PACKING MATERIAL: PS TAPE REEL 1 SET
Q'TY: 1*210=210 PCS



2. 包材:

外箱 1 PC
無鉛製程標籤  1PC
平卡/紙板 2PC
210*20=4200 PCS
PACKING MATERIAL: CARTON 1 PC
210*20=4200 PCS
Q'TY:



淨毛重
單位(KG)
數量
單位(PCS)

P / N	N.W.	G.W.	Q'TY
SHD-5014SGLH6-NS-L2-TR	**Kg	**±0.3Kg	4200

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FILE NO.	SHD-5014SGL	TITLE	SHD-5014SGLH6-NS-L2-TR	DESIGNED BY	Eric
PART NO.	(SERIES)	圖 名		CHECKED BY	Aaron
SHD-5014SGLH6-NS-L2-TR					2023-08-24

ZONE	REV.	DESCRIPTION	DATE	CHANGE
1	2	3	4	

TOLERANCE(公差):	UNIT	SCALE	1:1	SHEET	1/1	APPROVED BY
0.000 mm ± 0.00 mm ± 0.0 mm ±	單位	比例		頁次		



DC POWER JACK SPECIFICATION FOR REFLOW SOLDERING PROCESS

1. Materials and Finish:

1.1 Housing

- ◆ Thermoplastic
- ◆ Color: Black or Optional Color Available on Demand

1.2 Contact

- ◆ Alloy: (See Material Specifications for Reference)
- ◆ Contact Area: Optional Tin, Silver, Gold Flash or Nickel plating
- ◆ Solder Area: Tin Plating or Nickel Plating
- ◆ Under-Plating: Nickel over all

1.3 Center Pin

- ◆ Alloy: (See Material Specifications for Reference)
- ◆ Nickel Plating

1.4 Shell(option)

- ◆ Alloy (See Material Specifications for Reference)
- ◆ Nickel plating

※ Expiration For Plating: 6 months storage period under non-unpacked parts (40%~60%RH)

2. Rating:

- ◆ Current & Voltage:

Diameter of Center Pin(mm)	Rated voltage (V)	Rated current(A)
Less than or equal 1.30mm	12	1
1.65mm		2
greater than or equal 2.00mm		3

- ◆ Storage & Operating Temperature: -25°C~70°C



3. Electrical Performance:

Item		Test conditions	Performance
3.1	Contact Resistance	EIA-364-23B. Subject specimens to 100 mA maximum and 20 mV maximum dry circuit voltage	50mΩ Max (initial)
3.2	Insulation Resistance	EIA-364-21C. Subject specimens to DC 500V and measure insulation resistance between adjacent contacts, also measure between the contacts and the shield.	100MΩ Min.
3.3	Dielectric Withstanding Voltage	EIA-364-20B. Subject specimens to 500VAC (50—60Hz) for 1 minute between terminals and ground.	No discharge or breakdown

4. Mechanical Performance:

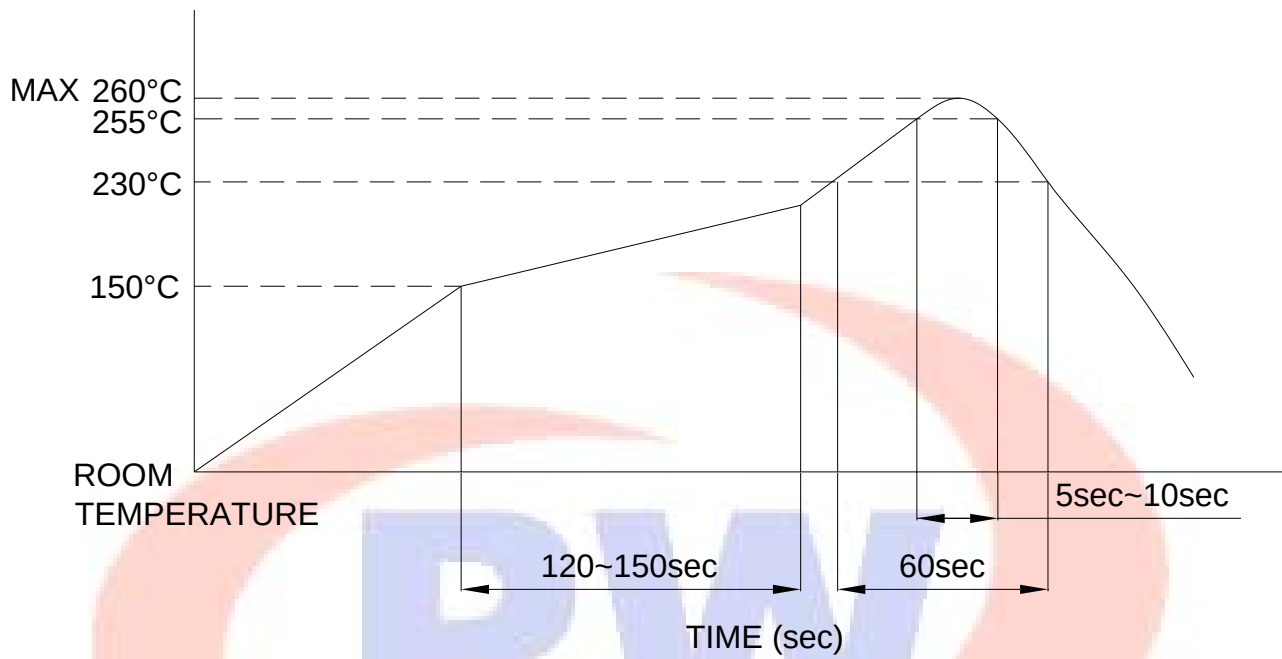
Item		Test conditions	Performance
4.1	Durability	EIA-364-09C. 500cycles operating at a rate of 200±50 cycles per hour , without load.	(1) Contact Resistance:100mΩ Max (2) There shall be no functional defects.
4.2	Mating Force	EIA-364-13B. Mating at the rate of 12.5mm per minute.	5.0kgf (Max.)
4.3	Unmating Force	EIA-364-13B. Mating at the rate of 12.5mm per minute.	10cycles 1.4kgf (Min.) 5.0kgf (Max.)

*5. Environmental Performance:*

Item		Test conditions	Performance
5.1	Heat Test	EIA-364-17B. 70°C±2°C for 96 hours. After test kept under 25 °C & 40%-60%RH for 30 minutes.	(1) Contact Resistance:100mΩ Max (2) There shall be no functional defects.
5.2	Humidity Test	EIA-364-31B. 40°C±2°C, 90-95% RH for 96 hours. After test kept under 25 °C & 40%-60%RH for 30 minutes.	(1) Contact Resistance:100mΩ Max (2) There shall be no functional defects.
5.3	Soldering Heat Resistance Test	EIA-364-56C. Equipment conditions refer to the following recommended reflow soldering profile.	(1) Contact Resistance:100mΩ Max (2) Mechanical and electrical characteristics shall be satisfied.
5.4	Solderability Test	EIA-364-52B. The top of the terminals shall be dipped 2mm in the solder bath of 245°C±5°C for 5±1.0 seconds.	A new uniform coating of solder shall cover a minimum of 95% of the surface being immersed.



REFLOW SOLDERING PROFILE



RECOMMENDED REFLOW SOLDERING CURVE

*6. Test Group and Sequence:*

ITEM	DESCRIPTION	TEST GROUP				
		A	B	C	D	E
		TEST SEQUENCE				
1	Visual inspection	1	1	1	1	1,3
2	Contact Resistance	2,7	2,4	2,4	2,4	
3	Insulation Resistance	3,8				
4	Withstanding Voltage	4,9				
5	Mating & Unmating Force	5,10				
6	Durability	6				
7	Heat Test		3			
8	Humidity Test			3		
9	Soldering Heat Resistance Test				3	
10	Solderability Test					2
Sample Size(pcs)		5	5	5	5	5

Note: